SBL 3216,4516,4532 SERIES

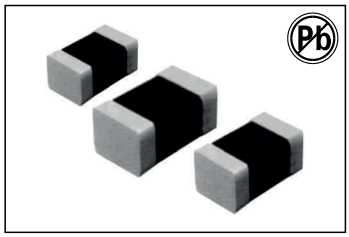
SURFACE–MOUNT MULTI–LAYER CHIP BEADS

FEATURES:

- Multilayer structure
- Closed magnetic circuit
- Avoids crosstalk
- Excellent magnetic shield
- Excellent solderability
- High reliability
- EMI/RFI suppression
- 20%impedance tolerance

COMMON APPLICATIONS:

- Cellular Phones
- Mobil Radios
- Cordless Telephones
- Modems
- Global Positioning Systems
- Wireless Communications Equipment
- Network Systems
- Computer Products



ELECTRICAL CHARACTERISTICS

Part Number	IMPEDANCE Ω AT 100 MHz	DCR (Ω) Max	IDC Max mA	Part Number	IMPEDANCE (Ω) AT 100 MHz	DCR (Ω) Max	IDC Max mA
SBL3216 190H	19	0.20	500	SBL3216 151L	150	0.10	2000
SBL3216 260H	26	0.20	500	SBL3216 301L	300	0.20	1000
SBL3216 310H	31	0.20	500	SBL3216 501L	500	0.20	1000
SBL3216 600H	60	0.30	400	SBL3216 601L	600	0.10	1000
SBL3216 700H	70	0.30	400	SBL3216 801L	800	0.10	1000
SBL3216 800H	80	0.30	300	SBL3216 102L	1000	0.50	500
SBL3216 900H	90	0.30	300				
SBL3216 121H	120	0.30	300	SBL4516 800H	80	0.30	300
SBL3216 151H	150	0.30	300	SBL4516 101H	100	0.10	300
SBL3216 221H	220	0.30	300	SBL4516 151H	150	0.30	300
SBL3216 301H	300	0.30	300	SBL4516 250H	25	0.30	500
SBL3216 501H	500	0.30	200	SBL4516 700H	70	0.30	300
SBL3216 601H	600	0.30	200	SBL4516 121H	120	0.30	300
SBL3216 801H	800	0.30	200	SBL4516 131H	130	0.30	300
SBL3216 102H	1000	0.30	200				
SBL3216 122H	1200	0.50	100	SBL4516 600L	60	0.01	6000
SBL3216 152H	1500	0.60	100	SBL4516 750L	75	0.025	3000
SBL3216 202H	2000	0.60	100	SBL4516 800L	80	0.05	3000
SBL3216 190L	19	0.04	3000	SBL4516 121L	120	0.10	2000
SBL3216 260L	26	0.04	3000	SBL4516 151L	150	0.10	2000
SBL3216 310L	31	0.04	3000	SBL4516 102L	1000	0.15	1500
SBL3216 600L	60	0.04	3000				
SBL3216 700L	70	0.04	3000	SBL4532 700L	70	0.035	6000
SBL3216 800L	80	0.04	3000	SBL4532 800L	80	0.050	6000
SBL3216 900L	90	0.05	2000	SBL4532 121L	120	0.050	3000
SBL3216 121L	120	0.10	2000	SBL4532 151L	150	0.050	3000

Note:1. K=±10%,M=±20%

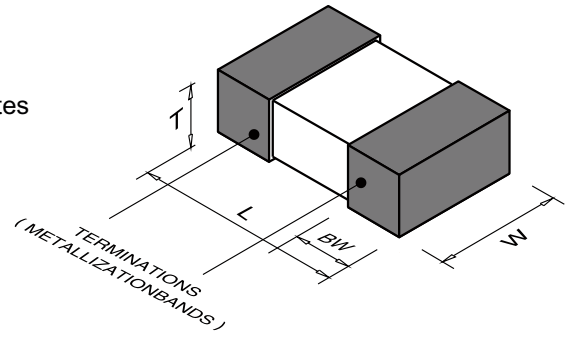
TECHNICAL INFORMATION

- Testing: Impedance vs. Frequency: HP 4195A
- Solderability: 90% of the terminal electrode shall be covered
  Preheat: @ 260 °C ±5 °C for 60 seconds
  Flux: Rosin, Dip for 10 seconds ±1 second
- Thermal Shock: Impedance shall within ±20% of initial value when temperature is -25 °C and +85 °C for 30 minutes for each 50 cycles
- Operating Temperature: -25 °C to +85 °C
- Storage Temperature: -25 °C to +85 °C

Note:All specifications subject to change without notice.

PHYSICAL CHARACTERISTICS

(Refer to Size Chart Page 4)



SURFACE–MOUNT MULTI–LAYER CHIP BEADS

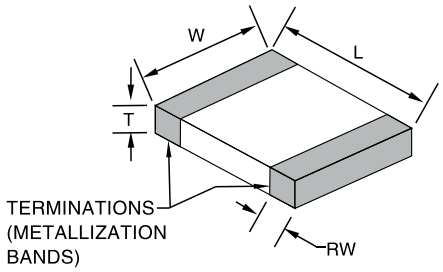
SBL SERIES

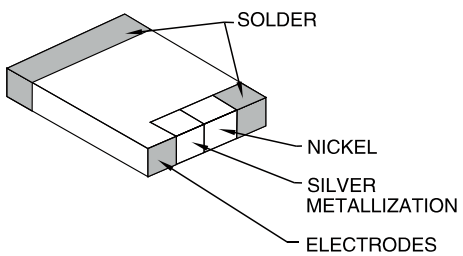
SIZE CHART1005,1608,2012,3216,3225,4516,4532

SIZE CHART: Sizes shown are in mm and (inches)

PART NUMBER	LENGTH(L)	WIDTH(W)	THICKNESS(T)	TERMINATION(BW)
SBL1005 (0402)	1.0 ± 0.15 (0.04 ± 0.006)	0.5 ± 0.15 (0.02 ± 0.006)	0.5 ± 0.15 (0.02 ± 0.006)	0.25 ± 0.1 (0.01 ± 0.004)
SBL1608 (0603)	1.6 ± 0.2 (0.063 ± 0.008)	0.8 ± 0.2 (0.031 ± 0.008)	0.8 ± 0.2 (0.031 ± 0.008)	0.3 ± 0.2 (0.012 ± 0.008)
SBL 2012 (0805)	2.0 ± 0.2 (0.079 ± 0.008)	1.2 ± 0.2 (0.047 ± 0.008)	0.9 ± 0.2 (0.035 ± 0.008)	0.5 ± 0.3 (0.020 ± 0.012)
SBL 3216 (1206)	3.2 ± 0.2 (0.126 ± 0.008)	1.6 ± 0.2 (0.063 ± 0.008)	1.1 ± 0.2 (0.025 ± 0.012)	0.5 ± 0.3 (0.020 ± 0.012)
SBL 3225 (1210)	3.2 ± 0.2 (0.126 ± 0.008)	2.5 ± 0.2 (0.098 ± 0.008)	1.3 ± 0.2 (0.051 ± 0.008)	0.5 ± 0.3 (0.020 ± 0.012)
SBL 4516 (1806)	4.560.2 (0.17760.008)	1.6 ± 0.2 (0.063 ± 0.008)	1.6 ± 0.2 (0.063 ± 0.008)	0.5 ± 0.3 (0.020 ± 0.012)
SBL 4532 (1812)	4.5 ± 0.2 (0.177 ± 0.008)	3.2 ± 0.2 (0.126 ± 0.008)	1.5 ± 0.2 (0.060 ± 0.008)	0.5 ± 0.3 (0.020 ± 0.008)

PHYSICAL CHARACTERISTICS: Refer to Size Chart Above





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